ON Semiconductor

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ON Semiconductor®

FCA20N60 N-Channel SuperFET MOSFET 600 V, 20 A, 190 m Ω

Features

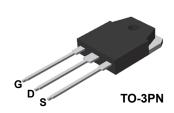
- 650V @ T₁ = 150°C
- Typ. $R_{DS(on)}$ = 150 m Ω
- Ultra Low Gate Charge (Typ. $Q_g = 75 \text{ nC}$)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 165 pF)
- 100% Avalanche Tested

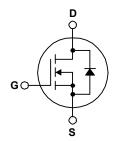
Applications

- · Solar Inverter
- AC-DC Power Supply

Description

SuperFET® MOSFET is ON Semiconductor's first genera-tion of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter			FCA20N60 / FCA20N60-F109	Unit
V_{DSS}	Drain to Source Voltage			600	V
V _{GSS}	Gate-Soure voltage			±30	V
I _D	Drain Current	- Continuous (T _C = 25°C)		20	^
	Drain Current	- Continuous (T _C = 100°C)		12.5	_ A
I _{DM}	Drain Current	- Pulsed	(Note 1)	60	Α
E _{AS}	Single Pulsed Avalanche I	Energy	(Note 2)	690	mJ
I _{AR}	Avalanche Current		(Note 1)	20	Α
E _{AR}	Repetitive Avalanche Ene	rgy	(Note 1)	20.8	mJ
dv/dt	Peak Diode Recovery dv/d	It	(Note 3)	4.5	V/ns
0		$(T_C = 25^{\circ}C)$		208	W
P_D	Power Dissipation	- Derate Above 25°C		1.67	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
T _L	Maximum Lead Temperato	ure for Soldering, 1/8" from Case fo	r 5 Seconds	300	°C

Thermal Characteristics

Symbol	Parameter	FCA20N60 / FCA20N60_F109	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.6	0C/M/	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	41.7	°C/W	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCA20N60	FCA20N60	TO-3PN	Tube	N/A	N/A	30 units
FCA20N60-F109	FCA20N60	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charae	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_J = 25^{\circ} C$	600	-	-	V
D V DSS	Drain to Source Breakdown voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_J = 150^{\circ} C$	-	650	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	0.6	-	V/°C
BV _{DS}	Drain-Source Avalanche Breakdown Voltage	V _{GS} = 0 V, I _D = 20 A	-	700	-	V
	Zero Gate Voltage Drain Current	V _{DS} = 600 V, V _{GS} = 0 V	-	-	1	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	10	μА
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	0.15	0.19	Ω
g _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 10 A	-	17	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	.,	-	2370	3080	pF
C _{oss}	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	-	1280	1665	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112	-	95	-	pF
C _{oss}	Output Capacitance	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	65	85	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	165	-	pF
Qg	Total Gate Charge at 10V	V _{DS} = 480 V, I _D = 20 A,	-	75	98	nC
Q _{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	13.5	18	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	36	-	nC

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		-	62	135	ns
t _r	Turn-On Rise Time	V _{DD} = 300 V, I _D = 20 A,	-	140	290	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{G} = 25 Ω	-	230	470	ns
t _f	Turn-Off Fall Time	(Note 4)	-	65	140	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current			-	20	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	60	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 20 A		-	-	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 20 A,	-	530	-	ns
Q_{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	10.5	-	μС

Notes:

- 1: Repetitive rating: pulse-width limited by maximum junction temperature.
- 2: I_{AS} = 10 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25 °C.
- 3: I $_{SD}~\leq 20$ A, di/dt ≤ 200 A/µs, V $_{DD} \leq BV _{DSS},$ starting T $_{J}$ = 25°C.
- 4: Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

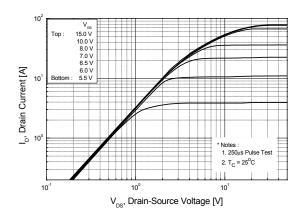


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

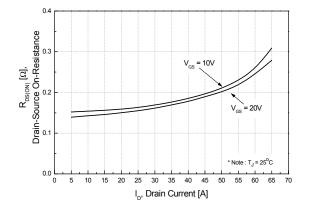


Figure 5. Capacitance Characteristics

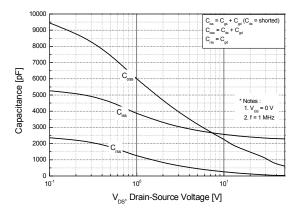


Figure 2. Transfer Characteristics

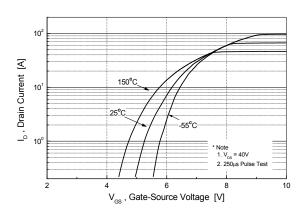


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

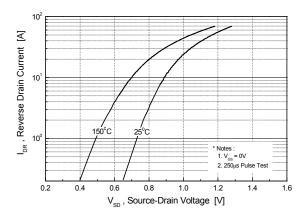
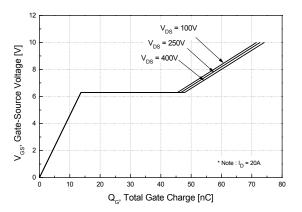


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

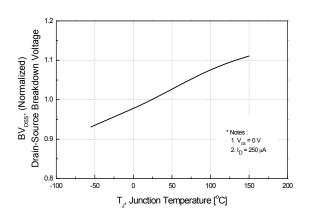


Figure 8. On-Resistance Variation vs. Temperature

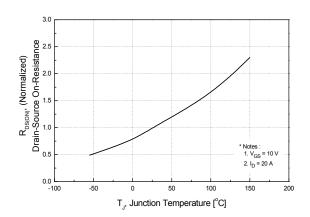


Figure 9. Maximum Safe Operating Area

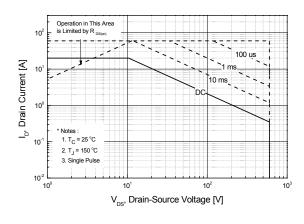


Figure 10. Maximum Drain Current vs. Case Temperature

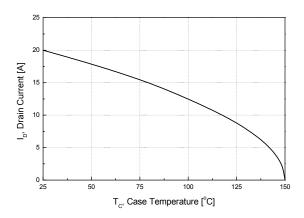
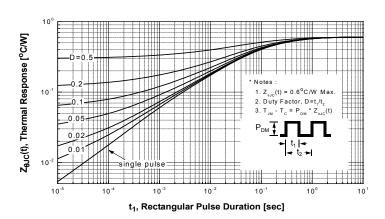


Figure 11. Transient Thermal Response Curve



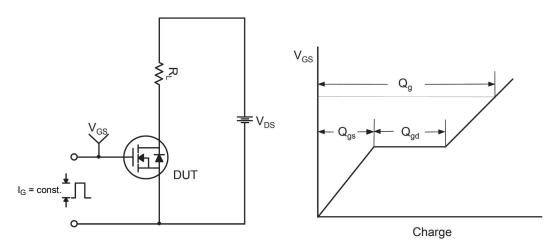


Figure 12. Gate Charge Test Circuit & Waveform

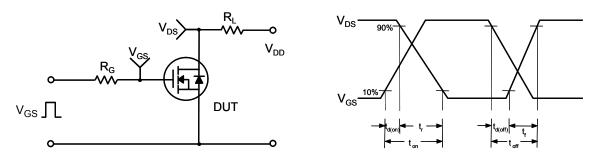


Figure 13. Resistive Switching Test Circuit & Waveforms

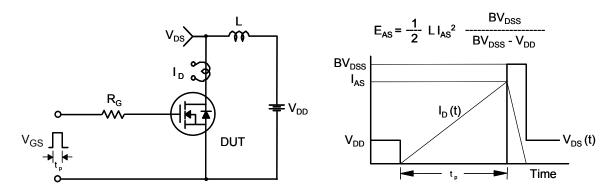
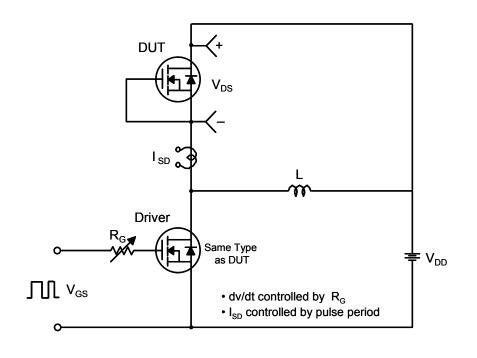


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



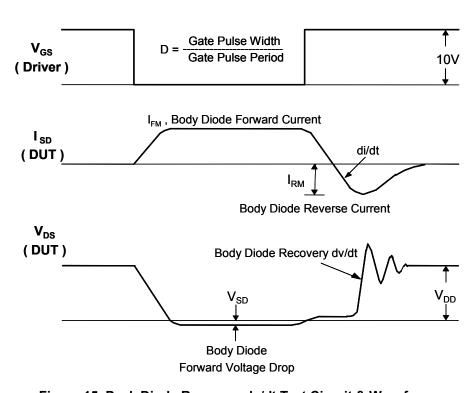


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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